

AMENDMENTS TO THE CLAIMS

Claims 1-12. (Cancelled)

Claim 13. (Currently Amended) A process for producing a substrate comprising a step of polishing a substrate to be polished with a polishing composition comprising:

water;

an abrasive;

a roll-off reducing agent comprising one or more compounds selected from the group consisting of carboxylic acids having 2 to 20 carbon atoms having either hydroxyl OH group or groups or SH group or groups, monocarboxylic acids having 1 to 20 carbon atoms, and dicarboxylic acids having 2 to 3 carbon atoms, and salts thereof; and

an intermediate alumina.

Claim 14. (Currently Amended) A process for producing a substrate comprising a step of polishing a substrate to be polished with a polishing composition comprising:

(A) one or more compounds selected from the group consisting of carboxylic acids having 2 to 20 carbon atoms having either

hydroxyl OH group or groups or SH group or groups, monocarboxylic acids having 1 to 20 carbon atoms, and dicarboxylic acids having 2 to 3 carbon atoms, and salts thereof;

(B) one or more compounds selected from the group consisting of polycarboxylic acids having 4 or more carbon atoms and having neither hydroxyl OH group or groups nor SH group or groups, aminopolycarboxylic acids, amino acids and salts thereof; and

(C) one or more compounds selected from the group consisting of an intermediate alumina and an alumina sol;
an abrasive; and
water.

Claim 15. (Previously Presented) The process of claim 14, wherein the intermediate alumina and the alumina sol in Compounds (C) have a specific surface area of from 30 to 300 m²/g and an average particle size of 0.01 to 5 μm.

Claim 16. (Previously Presented) The process of claim 14, wherein the intermediate alumina is prepared from aluminum hydroxide and/or alumina sol, each having a specific surface area of 10 m²/g or more and a content of an alkali metal and a content of an alkaline earth metal of 0.1% by weight or less.

Claim 17. (Currently Amended) A process for producing a substrate comprising a step of polishing a substrate to be polished with a polishing composition comprising:

(A) one or more compounds selected from the group consisting of carboxylic acids having 2 to 20 carbon atoms having either hydroxyl OH group or groups or SH group or groups, monocarboxylic acids having 1 to 20 carbon atoms, and dicarboxylic acids having 2 to 3 carbon atoms, and salts thereof; and

(B) one or more compounds selected from the group consisting of polycarboxylic acids having 4 or more carbon atoms and having neither hydroxyl OH group or groups nor SH group or groups, aminopolycarboxylic acids, amino acids and salts thereof;

an abrasive; and water.

Claim 18. (Currently Amended) The process of claim 17, wherein one or more compounds of Compounds (A) are selected from the group consisting of carboxylic acids having 2 to 20 carbon atoms having either hydroxyl OH group or groups or SH group or groups, and dicarboxylic acids having 2 to 3 carbon atoms, and salts thereof, and wherein one or more compounds of Compounds (B) are selected from the group consisting of polycarboxylic acids

having 4 or more carbon atoms and having neither hydroxyl OH group or groups nor SH group or groups, aminopolycarboxylic acids, and salts thereof.

Claim 19. (Currently Amended) The process of claim 17, wherein one or more compounds of Compounds (A) are selected from the group consisting of oxalic acid, malonic acid, glycolic acid, lactic acid, malic acid, glyoxylic acid, tartaric acid, citric acid, gluconic acid, and salts thereof, and wherein one or more compounds of Compounds (B) are selected from the group consisting of succinic acid, maleic acid, fumaric acid, citraconic acid, itaconic acid, tricarballylic acid, diglycolic acid, ethylene-diamine tetra acetic acid, diethylene triamine pentaacetic acid, and salts thereof.